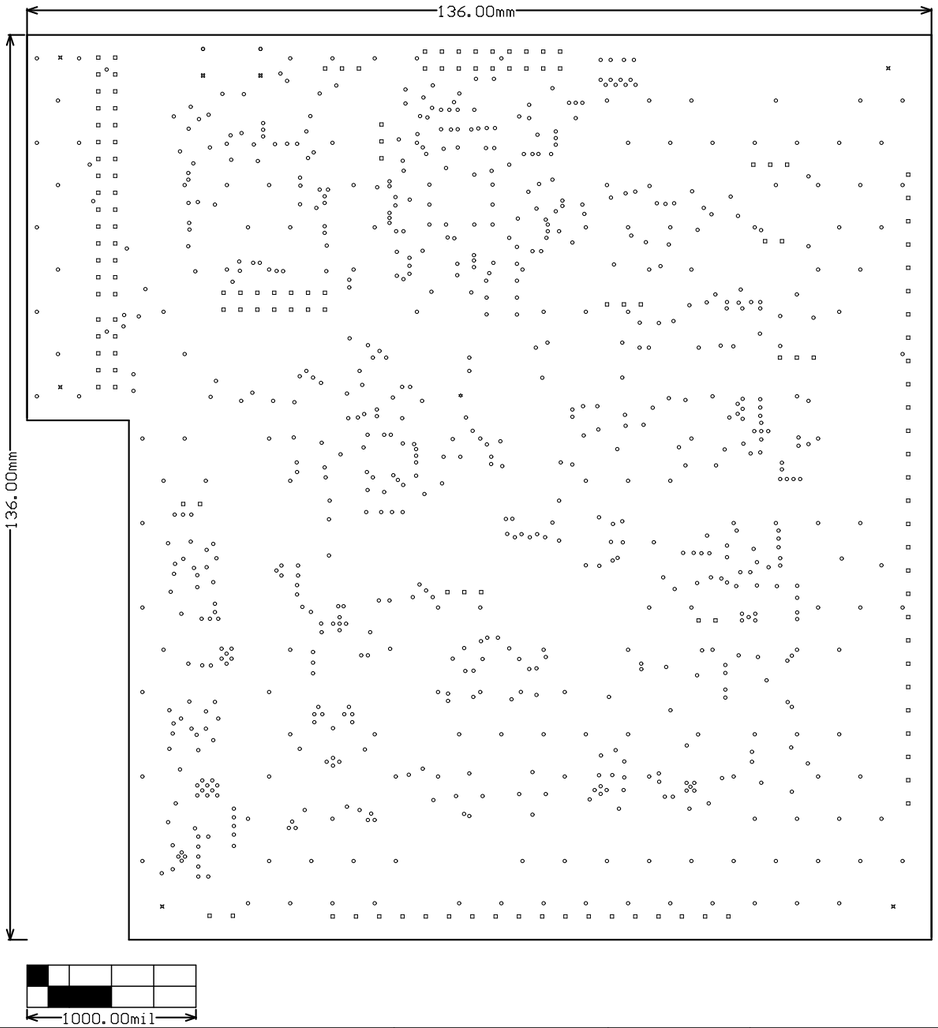
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.60mil	3.8	
1	Top Layer	CF-004	1.38mil		
	Dielectric 1	NP-155F	8.28mil	4.4	
2	Inner Layer 1	CF-004	0.60mil		
	Dielectric 2	NP-155F	41.93mil	4.43	
3	Inner Layer 2	CF-004	0.60mil		
	Dielectric 3	NP-155F	8.28mil	4.4	
4	Bottom Layer	CF-004	1.38mil		
	Bottom Solder	Solder Resist	0.60mil	3.8	
	Bottom Overlay				



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⌘	5	125.00mil (3.175mm)	NPTH	Round	Top Layer - Bottom Layer	
○	802	11.81mil (0.300mm)	PTH	Round	Top Layer - Bottom Layer	
□	144	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
✡	1	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
⌧	2	55.12mil (1.400mm)	PTH	Slot	Top Layer - Bottom Layer	
✪	2	70.87mil (1.800mm)	PTH	Slot	Top Layer - Bottom Layer	
	956 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

DESIGN INFORMATION

MIN. TRACK WIDTH: 6 MIL
MIN. CLEARANCE: 4 MIL
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
☐ FR-4 ☒ FR-4 High Tg ☐ OTHER _____
THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER _____
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- _____
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- _____

DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER _____

BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER _____
SOLDER RESIST COLOR: ☒ GREEN ☐ OTHER _____
☒ MATTE ☐ SEMI-GLOSS
SURFACE FINISH: ☒ IMMERSION GOLD (ENIG) ☐ ENEPIG
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER _____
ARRAY/PANEL: ☐ CUT AND TRIM PER M1 BOARD OUTLINE
☐ N.C. ROUTE ☒ V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ RoHS ☐ OTHER PER ORDER
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
☐ XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
☐ XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
☐ OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
☐ LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: AM62L-EVSE-DEV-EVM
DESIGNED FOR: Public Release
FILE NAME: PROC219E1.PcbDoc

ENGINEER: Simon Bozowicki	LAYOUT BY: Simon Bozowicki
SCALE: 1.12	ALTIUM DESIGNER VERSION: 24.3.1.35

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PROC219	REV: E1	SUN REV: Not in version control
LAYER NAME = [illegible] Dimensions	TID #: N/A		
PLOT NAME = Fabrication Drawing	GENERATED : 10/20/2025 12:24:58 PM	TEXAS INSTRUMENTS	

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